### PLEDxSW Series - White Body







OBSOLETE DATE: 03/26/2020 PCN/ECN# 41325 REPLACED BY: PLED series



#### **Agency Approvals**

Agency

Agency File Number

**LR**®

E133083

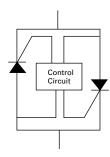
#### **Description**

PLEDxSW Series open LED protectors provide a switching electronic shunt path when an LED in an LED string fails as an open circuit. This ensures that the remaining string of LEDs will continue to function if a single LED does not.

PLEDxSW Series devices were designed to enable higher reliability in indoor LED lighting applications such as advertisement lighting and other applications. Additionally, they are molded from white material to make them less visible in the LED fixture and the white molding also reflects more light to improve overall light engine efficiency.

Compatible with one, two and three watt LEDs that have a nominal 3V forward characteristic, PLEDxSW Series devices are available in SMB surface mount package. The DO-214AA (SMB) low profile package is ideal for dense board applications.

#### **Schematic Symbol**



#### **Features & Benefits**

- Fast switching
- · Automatically resets after power cycle
- Low profile, small foot print standard DO-214AA package
- Compatible with industrial lighting environments
- Compatible with PWM frequencies up to 30 kHz
- RoHS compliant and halogen-free

#### Electrical Characteristics (All parameters are measured at T=25°C unless otherwise noted)

Part Number Marking		V break	<sup>BR</sup> down	V <sub>DRM</sub> breakdown	I <sub>H</sub>	l <sub>s</sub>	$I_{\scriptscriptstyle T}@V_{\scriptscriptstyle T}$	V <sub>T</sub> @ I <sub>T</sub> = 1 Amp	Critical rate of rise dV/dt	
	Volts		Volts	mAmps	mAmps	Amps	Volts	Volts		
		Min	Max	Min	Min	Max	Max	Max	Max	
PLED6SW	PL6	6	16	6						
PLED9SW	PL9	9	18	9	5	5 100	1.0	1.2	250\//	
PLED13SW	PL13	13	26	13			٥	100	1.0	1.2
PLED18SW	PL18	18	33	18						

#### **Thermal Considerations**

Package	Package Symbol		Value	Unit
DO-214AA in White	TJ	Operating Junction Temperature Range	-40 to +150	°C
	T <sub>s</sub>	Storage Temperature Range	-65 to +150	°C
	R <sub>eJA</sub>	Thermal Resistance: Junction to Ambient	DO-214AA: 90 <sup>1</sup> DO-214AA: 40 <sup>2</sup>	°C/W

#### Notes:

1) Standard FR-4 PCB with Copper Pads (Recommended Size)

2) Aluminum PCB

Thickness: 1.6mm

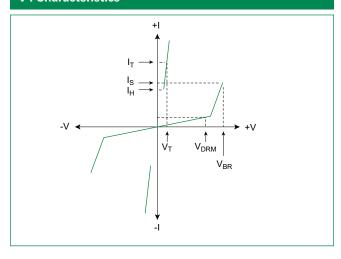
Grade: 1-2 W/mK Thermal Conductivity

Trace thickness: 2 oz

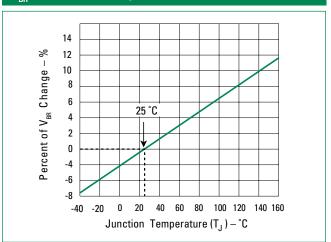
Insulation layer thickness: 215 um

Solder Pad Dimensions: 2.0mm x 2.8mm (Recommended Size)

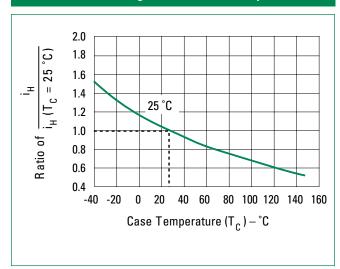
#### **V-I Characteristics**



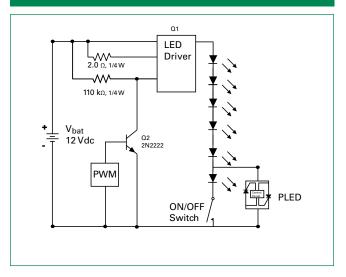
### V<sub>BR</sub> vs. Junction Temperature



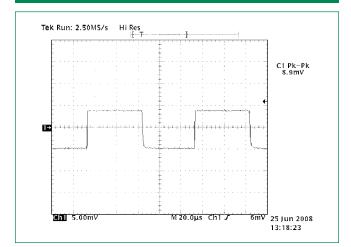
#### Normalized DC Holding Current vs. Case Temperature



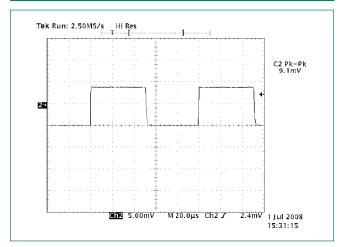
#### **LED Interference Test Circuit**



#### 6 LEDs in Series 50% Duty Cycle 10kHz

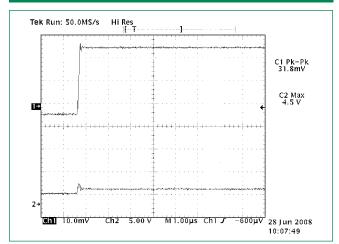


#### 5 LEDs and 1 PLED in Series 50% Duty Cycle 10kHz



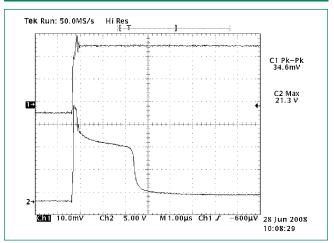
Note: These two graphs show the current magnitude through the LED string with and without the PLED included. There is no noticeable effect on the LED current magnitude when the PLED is included in the circuit as compared to the LED current magnitude when the PLED is not in the circuit. (The conversion factor for the test measurement in the graphs above is 10mA/mV for the Pearson coil measurement, therefore, the current magnitude in the first figure is 10mA\*8.9 = 89mA, while the second figure is 91mA.)

#### PLED in the Off-State 10kHz



Channel 1: current through LEDs (318 mA) Channel 2: voltage across PLED device (4.5 V)

#### PLED device zeners and then turns fully on 10kHz



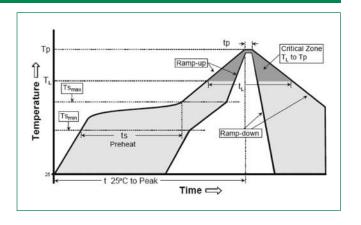
Channel 1: current through LEDs (346 mA) and PLED device once it is fully turned on 2.5 µsec later Channel 2: voltage across PLED device (21.3 V before PLED crowbars with 2 V drop)

#### **Soldering Parameters**

Reflow Co	ndition	Pb – Free assembly	
Pre Heat	-Temperature Min (T <sub>s(min)</sub> )	150°C	
	-Temperature Max (T <sub>s(max)</sub> )	200°C	
	-Time (min to max) (t <sub>s</sub> )	60 – 180 secs	
Average ramp up rate (Liquidus Temp (T <sub>L</sub> ) to peak		3°C/second max	
T <sub>S(max)</sub> to T <sub>L</sub> - Ramp-up Rate		3°C/second max	
Reflow	-Temperature (T <sub>L</sub> ) (Liquidus)	217°C	
	-Temperature (t <sub>L</sub> )	60 - 150 seconds	
Peak Temperature (T <sub>P</sub> )		260 <sup>+0/-5</sup> °C	
Time within 5°C of actual peak Temperature (t <sub>p</sub> )		30 seconds	
Ramp-dov	vn Rate	6°C/second max	
Time 25°C	to peakTemperature (T <sub>P</sub> )	8 minutes max	
Do not exc	ceed	260°C	



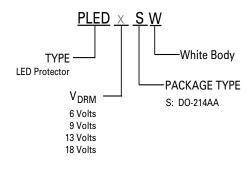
Terminal Material	Copper Alloy	
Terminal Finish	100% Matte Tin Plated	
Body Material	UL recognized epoxy meeting flammability classification 94V-0	



#### **Environmental Specifications**

High Temperature Voltage Blocking	MIL-STD-750: Method 1040, Condition A 80% min V <sub>DRM</sub> (VAC-peak), 150°C, 504 hours		
Temperature Cycling	MIL-STD-750: Method 1051 -65°C to 150°C, 15-minute dwell, 100 cycles		
Biased Temperature & Humidity	EIA/JEDEC: JESD22-A101 80%V <sub>DRM</sub> , 85°C, 85%RH, 1008 hours		
High Temperature Storage	MIL-STD-750: Method 1031 150°C, 1008 hours		
Low Temperature Storage	-65°C, 1008 hours		
Thermal Shock	MIL-STD-750: Method 1056 0°C to 100°C, 5-minute dwell, 10-second transfer, 10 cycles		
Resistance to Solder Heat	MIL-STD-750: Method 2031 260°C, 10 seconds		

#### **Part Numbering System**



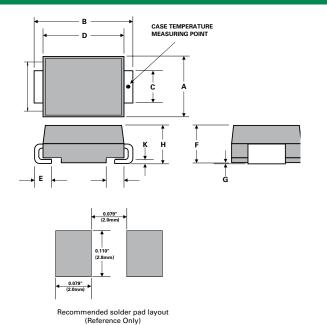
#### **Part Marking System**



#### **Packaging**

Package	Description	Packaging Quantity	Industry Standard
S	DO-214AA	2500	EIA-481-1

#### **Dimensions - DO-214 AA Package**



Dimensions	Incl	nes	Millimeters	
Difficusions	Min	Max	Min	Max
А	0.130	0.156	3.30	3.95
В	0.201	0.220	5.10	5.60
С	0.077	0.087	1.95	2.20
D	0.159	0.181	4.05	4.60
Е	0.030	0.063	0.75	1.60
F	0.075	0.096	1.90	2.45
G	0.002	0.008	0.05	0.20
Н	0.077	0.104	1.95	2.65
K	0.006	0.016	0.15	0.41

#### DO-214AA Embossed Carrier Reel Pack (RP)

#### Meets all EIA-481-1 Standards

